IOT完了済製品一覧(メーカブランド通信モジュール)

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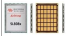
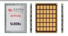
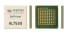
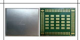
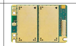
型番	メーカー名	Features	IOT完了年度	RAT	Form Factor	chipset		Photo	Module Firmware Version	UMTS					GSM				LTE						Interface	Class		Category			CA (Carrier aggregation)	GPS		Operating Temperature	Dimension ※LxWxH(mm)	Weight(g)	Voice or Data	Website	お問い合わせ先			
						Manufacturer	Model name			Band I (2G)	Band VI (800M)	Band IX (1.7G)	Band V (850M)	Band XIX (800M)	GSM900	GSM1800	PCS1900	GSM US850	Band1 (2G)	Band3 (1.7G)	Band17 (700M)	Band19 (800M)	Band21 (1.5G)	Band28 (700M)		GPRS	EDGE	UMTS Downlink	UMTS Uplink	LTE		Standalone	Assisted (Control Plane)						メーカー	部署／担当者	電話番号	メールアドレス
WLWHQ10	ASKEY Computer Corporation	Support LTE/3G data connection D/L 100Mbps, U/L 50Mbps Three U.FL Antenna Connectors Option support SMS, A-GPS	2013年度	LTE/UMTS	Mini PCI Express	Qualcomm	MDM9215		1.0.00	S	S	NS	S	S	NS	NS	NS	NS	S	NS	NS	S	S	NS	USB 2.0 x 1	NS	NS	Cat 24	Cat 6	Cat 3	NS	S	S	-20°C - +60°C (Extend to 70°C)	30 x 26.8 x 3.9	about 6.5	Data	http://www.askey.com.tw	ASKEY Computer Corporation	Marketing Division 3／Stella Liao	+886-2-2228-7588#18625	stella_liao@askey.com.tw
WLWNQ20	ASKEY Computer Corporation	Support LTE/3G data connection D/L 150Mbps, U/L 50Mbps Three IPEX MHF4 Antenna Connectors Option support SMS, A-GPS	2014年度	LTE/UMTS	M.2	Qualcomm	MDM9225M		1.0.00, 2.0.01	S	S	NS	S	S	NS	NS	NS	NS	S	S	NS	S	S	NS	USB 2.0 x 1	NS	NS	Cat 24	Cat 6	Cat 4	NS	S	S	-20°C - +60°C (Extend to 70°C)	30 x 42 x 2.3	about 6	Data	http://www.askey.com.tw	ASKEY Computer Corporation	Marketing Division 3／Stella Liao	+886-2-2228-7588#18625	stella_liao@askey.com.tw
WLWHQ30	ASKEY Computer Corporation	Support LTE FDD, CA/3G data connection D/L 300Mbps, U/L 100Mbps Five IPEX Antenna Connectors Option support SMS, A-GPS	2016年度	LTE/UMTS	Mini PCI Express	Qualcomm	MDM9230		1.0.00	S	S	NS	NS	S	NS	NS	NS	NS	S	S	NS	S	S	NS	USB 2.0 x 1	NS	NS	Cat 24	Cat 6	Cat 6	S	S	S	-20°C - + 70°C	30x50.95x4	about 7.5	Data	http://www.askey.com.tw	ASKEY Computer Corporation	Marketing Division 3／Stella Liao	+886-2-2228-7588#18625	stella_liao@askey.com.tw
EM7330	Sierra Wireless	Designed to be Windows 8 Mobile Broadband Interface Model (MBIM) compliant.	2013年度	LTE/UMTS	M.2	Qualcomm	MDM9215		05.05.65.00	S	S	NS	S	S	S	S	S	S	S	NS	NS	S	S	NS	USB 2.0 x 1	10	12	Cat.10	Cat 6	Cat 3	NS	S	NS	-30°C to +75°C	42 x 30 x 2.39	6	DATA	http://www.sierrawireless.com/productsandservices/AirPrime_Wireless_Modules/Essential_Modules/EM_Series.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
MC7330	Sierra Wireless	Designed to be Windows 8 Mobile Broadband Interface Model (MBIM) compliant.	2013年度	LTE/UMTS	Mini PCI Express	Qualcomm	MDM9215		05.05.65.00	S	S	NS	S	S	S	S	S	S	S	NS	NS	S	S	NS	USB 2.0 x 1	10	12	Cat 10	Cat 6	Cat 3	NS	S	NS	-40°C to +85°C	50.95 x 30 x 2.75	8.6	DATA	http://www.sierrawireless.com/productsandservices/AirPrime_Wireless_Modules/Essential_Modules/MC_Series.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
EM7340	Sierra Wireless	Designed to be Windows 8 Mobile Broadband Interface Model (MBIM) compliant.	2014年度	LTE/UMTS	M.2	Intel	XG716 + S4G		FIH7160_V1.3_AP_01.1644.02_JP	S	S	NS	NS	S	NS	NS	NS	NS	S	S	NS	S	S	NS	USB 2.0 x 1	NS	NS	Cat 10	Cat 6	Cat 4	NS	S	NS	-10°C to +70°C	42 x 30 x 2.39	6	DATA	http://www.sierrawireless.com/productsandservices/AirPrime_Wireless_Modules/Essential_Modules/EM_Series.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
HiLo 3G 850	Sierra Wireless	Smallest HSDPA module, low power consumption.	2014年度	UMTS Only	Original 40 pin connector	Qualcomm	QSC6270		001.90	S	S	NS	NS	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	12	12	Cat 6	384K	NS	NS	NS	NS	-40°C - +85°C	27 x 27 x 4.8	6.6	DATA	http://developer.sierrawireless.com/Resources/Resources/SagemcomM2M/HiLo/HiLo_3G_Technical_Specifications.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
SL8084T	Sierra Wireless	For M2M soldered-down module.Supporting the Open AT Application Framework.	2014年度	UMTS Only	74 pin LGA	Qualcomm	QSC6270		S4.1.0.21, C04.05.14.00	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	10	12	Cat 6	384K	NS	NS	S	NS	-40°C to +85°C	30 x 25 x 2.4	3.5	Voice (3G CS) /Data	http://www.sierrawireless.com/productsandservices/AirPrime_Wireless_Modules/Smart_Modules/SL_Series.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
SL8084BT	Sierra Wireless	For M2M soldered-down module.Supporting the Open AT Application Framework.	2014年度	UMTS Only	74 pin LGA	Qualcomm	QSC6270		S4.1.0.21, C04.05.14.00	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	10	12	Cat 6	384K	NS	NS	NS	NS	-40°C to +85°C	30 x 25 x 2.4	3.5	Voice (3G CS) /Data	http://www.sierrawireless.com/productsandservices/AirPrime_Wireless_Modules/Smart_Modules/SL_Series.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
HL8548	Sierra Wireless	For M2M soldered-down module	2015年度	UMTS Only	146 pin LGA	Intel	XMM6250		5.5.22.0, 5.5.24.0, 5.5.24.2	S	S	NS	S	S	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	33	33	Cat 8	Cat 6	NS	NS	NS	NS	-40°C to +85°C	23 x 22 x 2.5	3.5	Voice (3G CS) /Data	http://www.sierrawireless.com/productsandservices/airprime_wireless_modules/essential_modules/hl_series/	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
HL8548-G	Sierra Wireless	For M2M soldered-down module	2015年度	UMTS Only	146 pin LGA	Intel	XMM6250		5.5.22.0, 5.5.24.0, 5.5.24.2	S	S	NS	S	S	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	33	33	Cat 8	Cat 6	NS	NS	S	NS	-40°C to +85°C	23 x 22 x 2.5	3.5	Voice (3G CS) /Data	http://www.sierrawireless.com/productsandservices/airprime_wireless_modules/essential_modules/hl_series/	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
HL7539	Sierra Wireless	For M2M soldered-down module	2015年度	LTE Only	146 pin LGA	Intel	XMM7160		2.7, 2.8, 2.9, 2.11	NS	NS	NS	NS	NS	NS	NS	NS	NS	S	NS	NS	S	S	NS	USB 2.0 x 1 / Serial x 1	NS	NS	NS	NS	S	NS	NS	NS	-40°C to +85°C	23 x 22 x 2.5	3.5	Data	http://www.sierrawireless.com/productsandservices/airprime_wireless_modules/essential_modules/hl_series/	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
AR8552	Sierra Wireless	Automotive-grade M2M soldered-down module.	2015年度	UMTS Only	133 pin LGA	Qualcomm	MDM6200		ARx550_R2_FP.00.05.18.03 ARx550_R2_FP.00.05.18.06	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	10	12	Cat 10	Cat 6	NS	NS	S	NS	-40°C to +85°C	40 x 40 x 4.12	11.8	Voice (3G CS) /Data	http://www.sierrawireless.com/productsandservices/airprime_wireless_modules/smart_modules/ar_series.aspx	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
AR7588	Sierra Wireless	AR7588 module is designed for the automotive industry. It support LTE, WCDMA, and GSM air interface standards. AR7588 support LTE Category 4. It also have Global Navigation Satellite System (GNSS)capabilities including GPS, GLONASS, Galileo, BeiDou and QZSS.	2019年度	LTE/UMTS	LGA	Qualcomm	MDM9628		SWI9X28A_01.15.01.00	S	S	NS	S	NS	S	S	NS	NS	S	S	NS	S	S	S	USB2.0 x1/ UART x 3	12	12	Cat 24	Cat 6	Cat 4	NS	S	S	-40°C - + 85°C	37 x 32 x3.53	10g	Voice (3G CS) /Data	https://www.sierrawireless.com/products-and-solutions/embedded-solutions/products/ar7588/	Sierra Wireless Japan K.K	Sales／Hidekazu Horisawa	+81-3-6717-6030	hhorisawa@sierrawireless.com
SEM-82J	Wistron NeWeb Corporation	Low power consumption Automotive proven LGA form factor Proven module for smart engery Easy mirgration to LTE	2013年度	UMTS only	LGA	Qualcomm	MDM8215		CBJ-V1.0	S	S	NS	NS	S	NS	NS	NS	NS	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	NS	NS	Cat 8	Cat 6	NS	NS	NS	NS	-30°C - +85°C	34 x 34 x 3	6	Data	http://www.wnc.com.tw	Wistron NeWeb Corporation	Peggy Chen	+81-8079438910	peggy.chen@wnc.com.tw
UMC-A14A5	Wistron NeWeb Corporation	・3GPP category support: LTE CAT-1 with 10/5 Mbps for DL/UL ・Embedded 512 Mbit LPDDR / 256 Mbit SPI NOR Flash ・Embedded network processor with Linux OS ・Interface: HS USB2.0 with integrated PHY / Dual UART interfaces (4 bit and 2 bit) for high-speed data transfer and diagnostic tools support / SPI master interface / USIM interface / GPIOs	2018年度	LTE only	LGA	Altair	ALT1160		CM2.0.0.0.96/ FW2.0.0.0.95	NS	NS	NS	NS	NS	NS	NS	NS	NS	S	NS	NS	S	NS	NS	USB 2.0 x 1 ／ Serial x 1	NS	NS	NS	NS	Cat1	NS	S	NS	-25°C - +75°C	26.3 x 23.1 x 2.3	6	Data	http://www.wnc.com.tw	Wistron NeWeb Corporation	Peggy Chen	+81-8079438910	peggy.chen@wnc.com.tw
CL32DAH31	太陽誘電株式会社	・LTE Cat 1 ・通信速度(最大):DL10Mbps／UL5Mbps ・eDRX対応 ・TCP/IP, UDP/IP, SSL/TLS 1.2, SMS	2018年度	LTE only	LGA	Altair	ALT1160L		CM_02_00_00_00_96, CM_02_00_00_00_109	NS	NS	NS	NS	NS	NS	NS	NS	NS	S	NS	NS	S	NS	NS	UART / USB2.0 / SIM Card I/F / GPIO	NS	NS	NS	NS	Cat 1	NS	NS	NS	-30°C - + 70°C	26 x 20 x 2.4	2.8	Data	https://www.yuden.co.jp/jp/solutions/lte/product/	太陽誘電株式会社		03-6757-8343	
HC28-J	Thales DIS (Cinterion wireless module)	1.Footprint Compatibility with Global module 2.Extended Tempreture range 3.Embedded GPS support 4.MS windows/Linux Support	2011年度以前	UMTS/GSM	original 50pin connector	Qualcomm	MSM6280		2.002	S	S	NS	NS	NS	S	S	NS	NS	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	10	10	Cat 6	384K	NS	NS	S	NS	-30°C - +85°C	50 × 34.0 × 4.5	10	Voice (3G CS) /Data	None	Thales DIS (Cinterion wireless module)	Mobile Connectivity & Analytics-IoT Solutions / Hideyuki Numata	03-6744-8906	info-wm.japan@thalesgroup.com
PH8-J Rel.2	Thales DIS (Cinterion wireless module)	1.Footprint Compatibility (80pin) 2.Extended Tempreture range 3.TCP/IP protocol support 4.Embedded GPS with A-GPS support 5.MS windows/Linux/Android Support	2012年度	UMTS/GSM	original 80pin connector	Qualcomm	MDM6200		2.101	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	12	12	Cat 10	Cat 6	NS	NS	S	S	-40°C - +85°C	50 × 33.9 × 3.1	9.5	Data	None	Thales DIS (Cinterion wireless module)	Mobile Connectivity & Analytics-IoT Solutions / Hideyuki Numata	03-6744-8906	info-wm.japan@thalesgroup.com
PH8-J Rel.3	Thales DIS (Cinterion wireless module)	1.Footprint Compatibility (80pin) 2.Extended Tempreture range 3.Support Embedded SIM 4.Embedded GPS with A-GPS support 5.MS windows/Linux/Android Support	2012年度	UMTS/GSM	original 80pin connector	Qualcomm	MDM6200		3.001	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	12	12	Cat 10	Cat 6	NS	NS	S	S	-40°C - +85°C	50 × 33.9 × 3.1	9.5	Voice (3G CS) /Data	None	Thales DIS (Cinterion wireless module)	Mobile Connectivity & Analytics-IoT Solutions / Hideyuki Numata	03-6744-8906	info-wm.japan@thalesgroup.com
PHS8-J Rel.3	Thales DIS (Cinterion wireless module)	1.Footprint Compatibility (LGA-156pad) 2.Extended Tempreture range 3.Support Embedded SIM 4.Embedded GPS with A-GPS support 5.MS windows/Linux/Android Support	2012年度	UMTS/GSM	LGA	Qualcomm	MDM6200		3.001	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	12	12	Cat 10	Cat 6	NS	NS	S	S	-40°C - +85°C	29 × 33 × 2	5	Voice (3G CS) /Data	None	Thales DIS (Cinterion wireless module)	Mobile Connectivity & Analytics-IoT Solutions / Hideyuki Numata	03-6744-8906	info-wm.japan@thalesgroup.com
EHS6	Thales DIS (Cinterion wireless module)	1.Footprint Compatibility (LGA-114pad) 2.Extended Tempreture range 3.Support Embedded SIM 4.Java ME support 5.MS windows/Linux/Android Support	2015年度	UMTS/GSM	LGA	INTEL	XMM6250		3.001 4.003	S	S	NS	S	NS	S	S	S	S	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 2	12	12	Cat 8	Cat 6	NS	NS	NS	NS	-40°C - + 85°C	25.4 x 27.6 x 2.2	3.5	Data	https://www.gemalto.com/iot/iot-connectivity/products/iot-modules/ehs6	Thales DIS (Cinterion wireless module)	Mobile Connectivity & Analytics-IoT Solutions / Hideyuki Numata	03-6744-8906	info-wm.japan@thalesgroup.com
PDS6-J	Thales DIS (Cinterion wireless module)	1.Footprint Compatibility (LGA-156pad) 2.Extended Tempreture range 3.Support Embedded SIM 4.Java ME support 5.MS windows/Linux/Android Support	2015年度	UMTS/GSM	LGA	INTEL	XMM6250		3.001 4.003	S	S	NS	S	S	NS	NS	NS	NS	NS	NS	NS	NS	NS	NS	USB 2.0 x 1 / Serial x 1	NS	NS	Cat 8	Cat 6	NS	NS	NS	NS	-40°C - + 85°C	29 × 33 × 2.3	5	Voice (3G CS) /Data	https://www.gemalto.com/iot/iot-connectivity/products/iot-modules/pds6	Thales DIS (Cinterion wireless module)	Mobile Connectivity & Analytics-IoT Solutions / Hideyuki Numata	03-6744-8906	info-wm.japan@thalesgroup.com

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